

## **General Description**

The WSF18N15 is the highest performance trench N-Ch MOSFET with extreme high cell density, which provide excellent RDSON and gate charge for most of the synchronous buck converter applications.

The WSF18N15 meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

#### **Features**

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent Cdv/dt effect decline
- Green Device Available

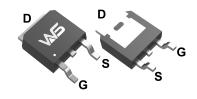
## **Product Summery**

BV <sub>DSS</sub>	R <sub>DSON</sub>	I <sub>D</sub>		
150V	95mΩ	17A		

## **Applications**

- High-Frequency Switch
- Load Switch
- Motion Switch

# **TO-252 Pin Configuration**





# **Absolute Maximum Ratings**

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	150	V
$V_{GS}$	Gate-Source Voltage	±20	V
I <sub>D</sub> @T <sub>C</sub> =25°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	17	А
I <sub>D</sub> @T <sub>C</sub> =100°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	12	А
I <sub>D</sub> @T <sub>A</sub> =25°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	3.0	А
I <sub>D</sub> @T <sub>A</sub> =70°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	2.5	А
I <sub>DM</sub>	Pulsed Drain Current <sup>2</sup>	40	А
EAS	Single Pulse Avalanche Energy <sup>3</sup>	53	mJ
I <sub>AS</sub>	Avalanche Current	18	А
P <sub>D</sub> @T <sub>C</sub> =25°C	Total Power Dissipation <sup>3</sup>	72.6	W
P <sub>D</sub> @T <sub>A</sub> =25°C	Total Power Dissipation <sup>3</sup>	2.1	W
T <sub>STG</sub>	Storage Temperature Range	-55 to 150	°C
T <sub>J</sub>	Operating Junction Temperature Range	-55 to 150	°C

### **Thermal Data**

Symbol	Parameter	Тур. Мах.		Unit	
R <sub>0JA</sub>	Thermal Resistance Junction-ambient <sup>1</sup>		60	°C/W	
$R_{ heta JC}$	Thermal Resistance Junction-Case <sup>1</sup>		1.72	°C/W	



# Electrical Characteristics (T<sub>J</sub>=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V , I <sub>D</sub> =250uA	150			V
$\triangle BV_{DSS}/\triangle T_{J}$	BVDSS Temperature Coefficient	Reference to 25°C , I <sub>D</sub> =1mA		0.098		V/°C
В	Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =10V , I <sub>D</sub> =10A		95	105	mΩ
R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance	V <sub>GS</sub> =4.5V , I <sub>D</sub> =10A		105	115	mΩ
$V_{GS(th)}$	Gate Threshold Voltage	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =250uA	1.2		2.5	V
$\triangle V_{GS(th)}$	V <sub>GS(th)</sub> Temperature Coefficient	VGS-VDS , ID -230UA		-4.57		mV/°C
	Drain-Source Leakage Current	V <sub>DS</sub> =120V , V <sub>GS</sub> =0V , T <sub>J</sub> =25°C			1	uA
I <sub>DSS</sub>	Drain-Source Leakage Current	V <sub>DS</sub> =120V , V <sub>GS</sub> =0V , T <sub>J</sub> =55°C			5	
I <sub>GSS</sub>	Gate-Source Leakage Current	$V_{GS}=\pm 20V$ , $V_{DS}=0V$			±100	nA
gfs	Forward Transconductance	V <sub>DS</sub> =5V , I <sub>D</sub> =10A		33		8
Qg	Total Gate Charge (10V)			25.1		
Q <sub>gs</sub>	Gate-Source Charge	V <sub>DS</sub> =75V , V <sub>GS</sub> =4.5V , I <sub>D</sub> =10A		6.8		nC
$Q_{gd}$	Gate-Drain Charge			12.6		
$T_{d(on)}$	Turn-On Delay Time			13		
Tr	Rise Time	V <sub>DD</sub> =25V , V <sub>GS</sub> =10V ,		8.2		no
$T_{d(off)}$	Turn-Off Delay Time	$R_G=3.3\Omega I_D=10A.$		25		ns
T <sub>f</sub>	Fall Time			11		
C <sub>iss</sub>	Input Capacitance			2285		
C <sub>oss</sub>	Output Capacitance	V <sub>DS</sub> =25V , V <sub>GS</sub> =0V , f=1MHz		110		pF
C <sub>rss</sub>	Reverse Transfer Capacitance			83		

#### **Guaranteed Avalanche Characteristics**

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
EAS	Single Pulse Avalanche Energy <sup>5</sup>	V <sub>DD</sub> =25V , L=0.5mH , I <sub>AS</sub> =6A	15			mJ

### **Diode Characteristics**

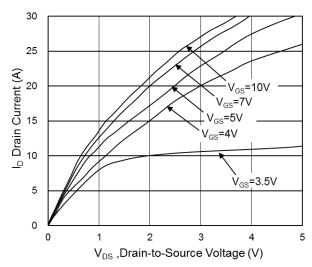
Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
I <sub>S</sub>	Continuous Source Current <sup>1,6</sup>	V =V =0V Force Current			17	Α
I <sub>SM</sub>	Pulsed Source Current <sup>2,6</sup>	V <sub>G</sub> =V <sub>D</sub> =0V , Force Current			40	Α
$V_{SD}$	Diode Forward Voltage <sup>2</sup>	V <sub>GS</sub> =0V , I <sub>S</sub> =1A , T <sub>J</sub> =25°C			1.3	V
t <sub>rr</sub>	Reverse Recovery Time			37		nS
Q <sub>rr</sub>	Reverse Recovery Charge	IF=10A , dI/dt=100A/μs , T <sub>J</sub> =25°C		263		nC

#### Note:

- 1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width  $\leqq$  300us , duty cycle  $\leqq$  2%
- 3 .The EAS data shows Max. rating . The test condition is  $V_{DD}$ =25V, $V_{GS}$ =10V,L=0.3mH, $I_{AS}$ =18A
- 4.The power dissipation is limited by 150°C junction temperature
- 5 .The data is theoretically the same as  $I_{\text{D}}$  and  $I_{\text{DM}}$  , in real applications , should be limited by total power dissipation.



# **Typical Characteristics**



**Fig.1 Typical Output Characteristics** 

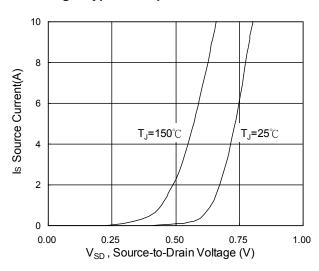


Fig.3 Forward Characteristics of Reverse

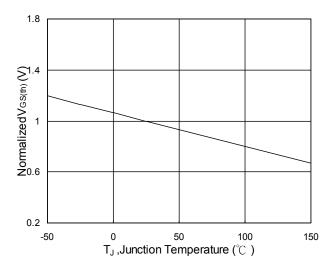


Fig.5 Normalized V<sub>GS(th)</sub> vs. T<sub>J</sub>

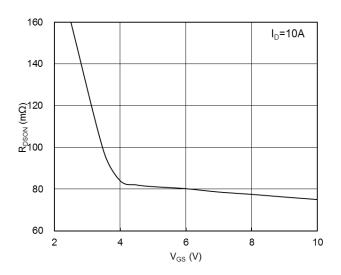


Fig.2 On-Resistance vs. Gate-Source Voltage

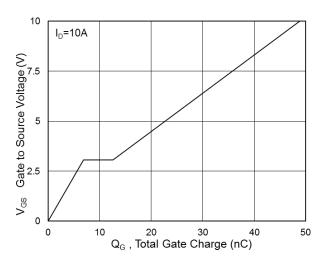


Fig.4 Gate-Charge Characteristics

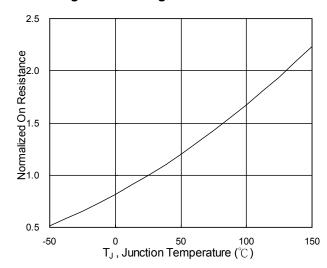
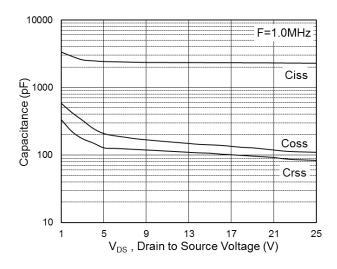


Fig.6 Normalized R<sub>DSON</sub> vs. T<sub>J</sub>





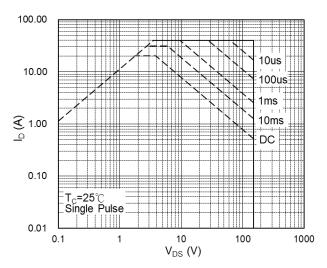


Fig.7 Capacitance

Fig.8 Safe Operating Area

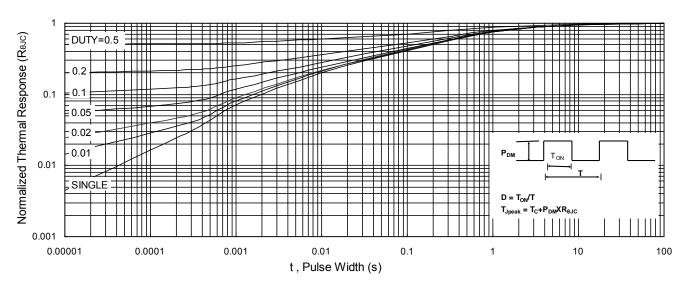


Fig.9 Normalized Maximum Transient Thermal Impedance

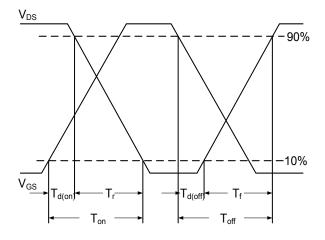


Fig.10 Switching Time Waveform

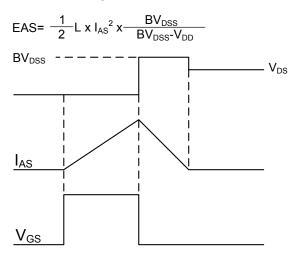


Fig.11 Unclamped Inductive Switching Waveform



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